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(54) METHOD FOR FORMING BUMP ON ELECTRODE PAD USING BILAYER MULTILAYER FILM

(57)Abstract:

PROBLEM TO BE SOLVED: To form bumps using a resist film having high resolution and high peelability.

SOLUTION: This method for forming bumps on electrode pads has at least following steps, carried out on a wiring board having a plurality of electrode pads on the surface thereof: namely, a step of forming opening patterns at the positions, corresponding to the electrode pads after a bilayer multilayer film is formed on a substrate, wherein the lower layer of the film, consisting of an alkaline soluble and radiation insensitive resin composition material and the upper layer, consisting of a negative type radiation sensitive resin composition material; a step of introducing a low melting metal into the opening patterns; a step of forming the bumps by making the low melting metal reflow through a pressing or heating process; and the step of peeling/removing the bilayer multilayer film from the substrate.

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